

IN THE CLAIMS

The following is a complete listing of the claims, and replaces all earlier versions and listings.

1. (previously presented) A method for manufacturing a printed circuit board element, comprising the steps of:

 providing a printed circuit board substrate with at least one conductor layer;

 structuring the conductor layer;

 roughening the whole structured conductor layer in the surface area;

 applying a noble metal layer on the whole structured, roughened conductor layer , the surface of the noble metal layer being provided with a corresponding roughness; and

 applying at least one electric PTF component in the area of the surface-roughened noble metal layer by imprinting.
2. (canceled)
3. (canceled)
4. (previously presented) The method according to claim 1, wherein the surface of the conductor layer is roughened by ionic etching.
5. (previously presented) The method according to claim 1, wherein the surface of the conductor layer is roughened by mechanical processing.

6. (previously presented) The method according to claim 1, wherein the surface of the conductor layer is roughened by electroplating.
7. (previously presented) The method according to claim 1, wherein the noble metal layer is applied on the conductor layer with a thickness of between 0.02 μm and 1 μm .
8. (previously presented) The method according to claim 1, wherein the noble metal layer is applied on the conductor layer in a chemical-currentless manner.
9. (previously presented) The method according to claim 1, wherein the noble metal layer is applied on the conductor layer by electroplating.
10. (previously presented) The method according to claim 1, wherein the noble metal layer is applied on the conductor layer by cathodic evaporation.
11. (previously presented) The method according to claim 1, wherein the noble metal layer is applied on the conductor layer by sputtering.
12. (previously presented) The method according to claim 1, wherein a layer made of at least one metal from the group comprising silver, gold, palladium, and platinum, is used as the noble metal layer.
13. (canceled)

14. (previously presented) The method according to claim 1, wherein the electric component is a resistor.
15. (previously presented) The method according to claim 1, wherein, after having applied the noble metal layer on the roughened conductor layer and after having applied the electric component to the surface-roughened noble metal layer, a further printed circuit board structure is applied and a pressing to a multi layer is performed.
16. (previously presented) The method according to claim 1, wherein, after having applied the noble metal layer on the roughened conductor layer and after having applied the electric component on the surface-roughened noble metal layer, a solder stop mask is mounted.
17. (previously presented) The method according to claim 1, wherein a printed circuit board substrate with two conductor layers is used, and at least one conductor layer is structured and roughened.
18. (previously presented) The method according to claim 1, wherein, after having been structured, the conductor layer is roughened in the surface area.
19. (canceled)
20. (canceled)

21. (canceled)

22. (canceled)

23. (canceled)

24. (canceled)

25. (canceled)

26. (canceled)

27. (canceled)

28. (canceled)

29. (canceled)